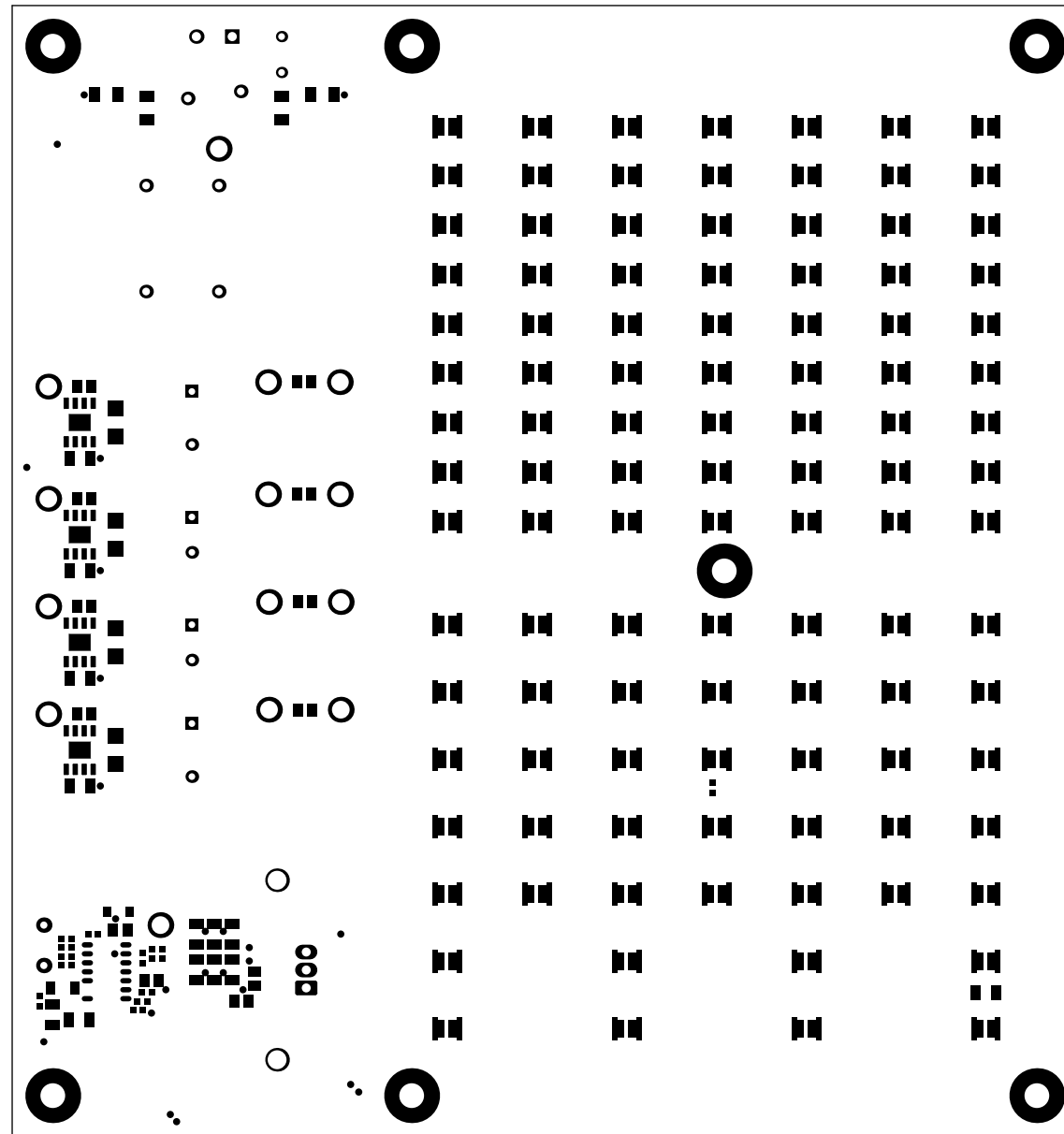
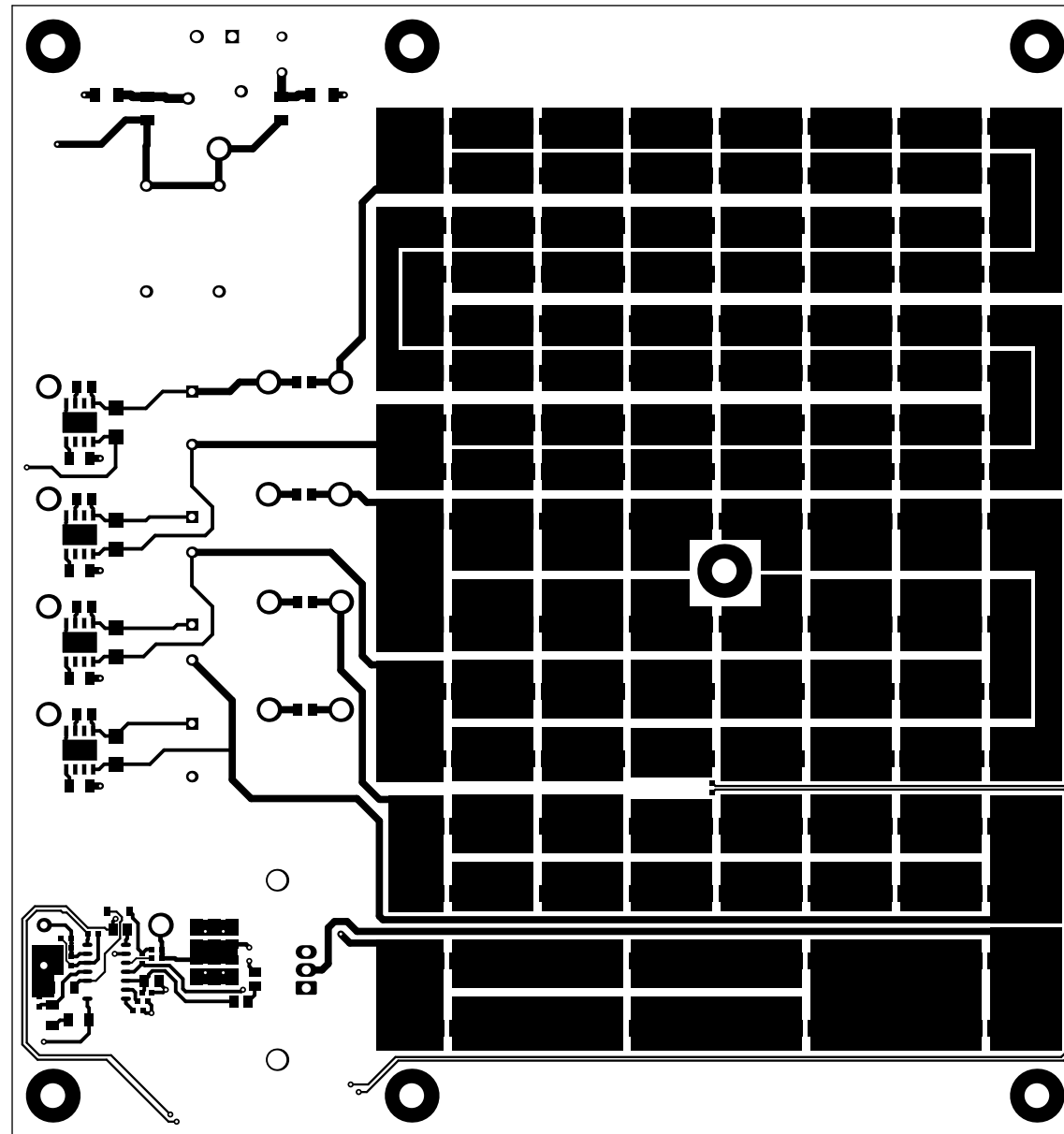


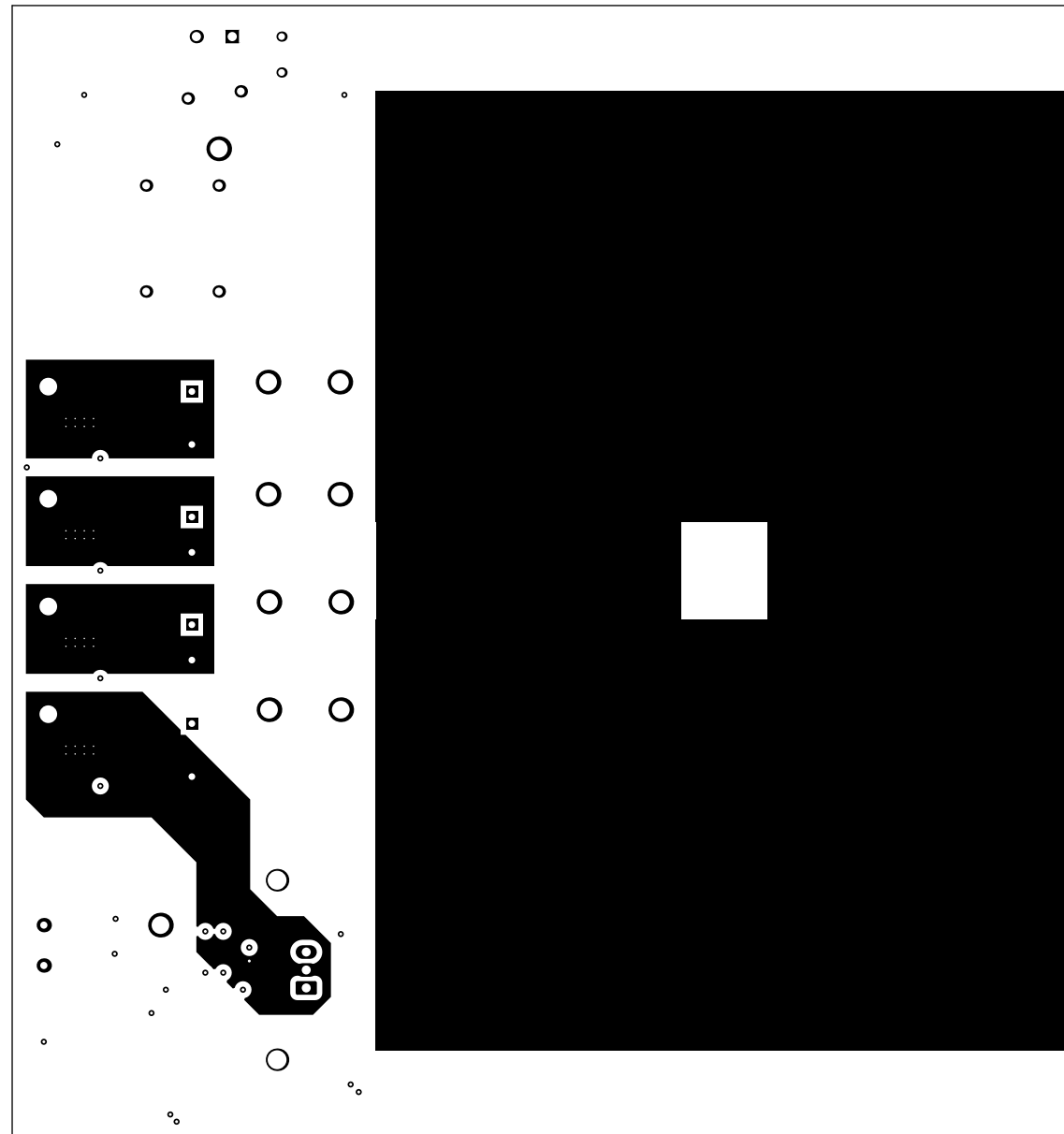
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 6/30/2017 1:52:03 PM	TEXAS INSTRUMENTS	



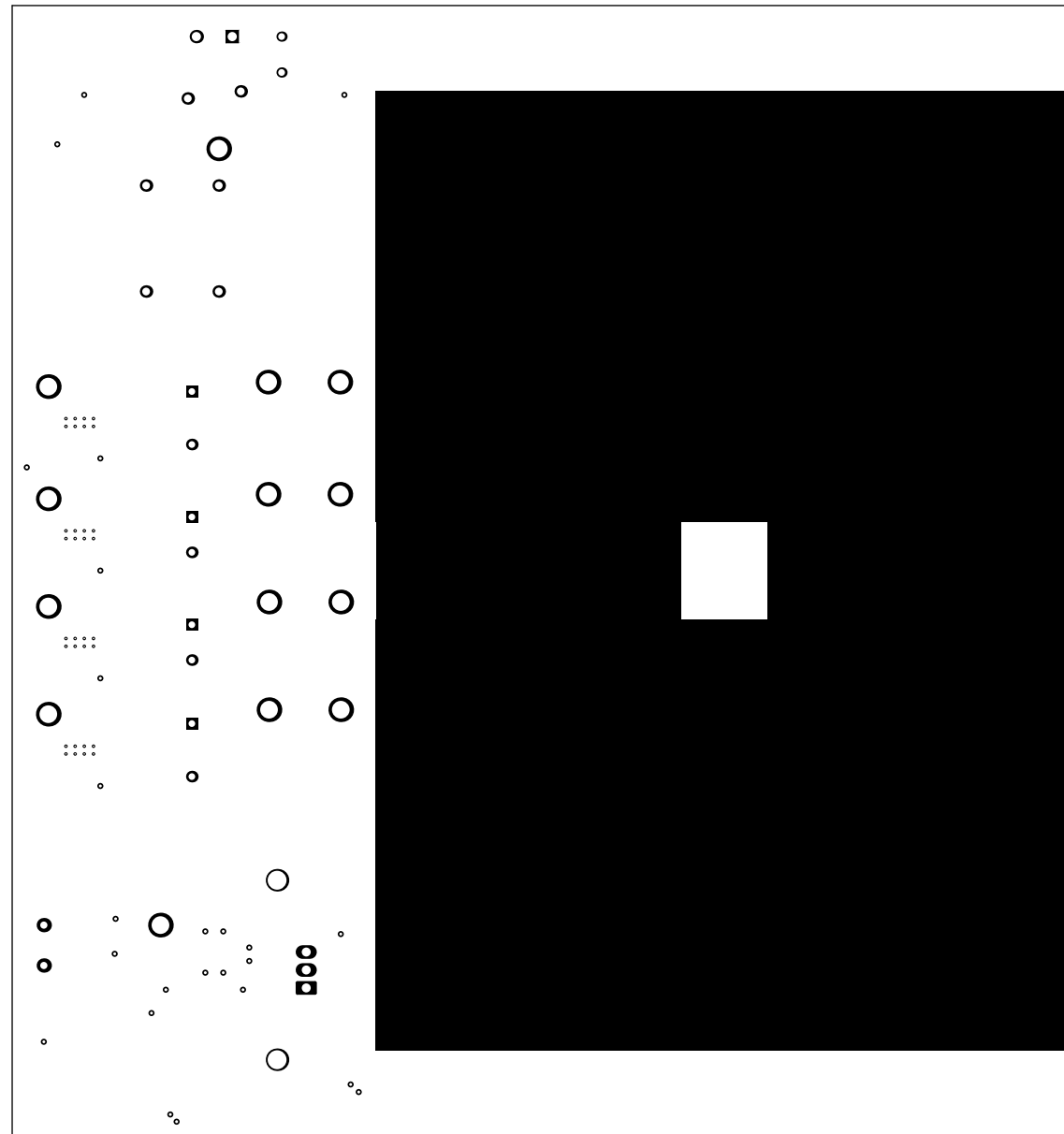
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 6/30/2017 1:52:04 PM	TEXAS INSTRUMENTS	



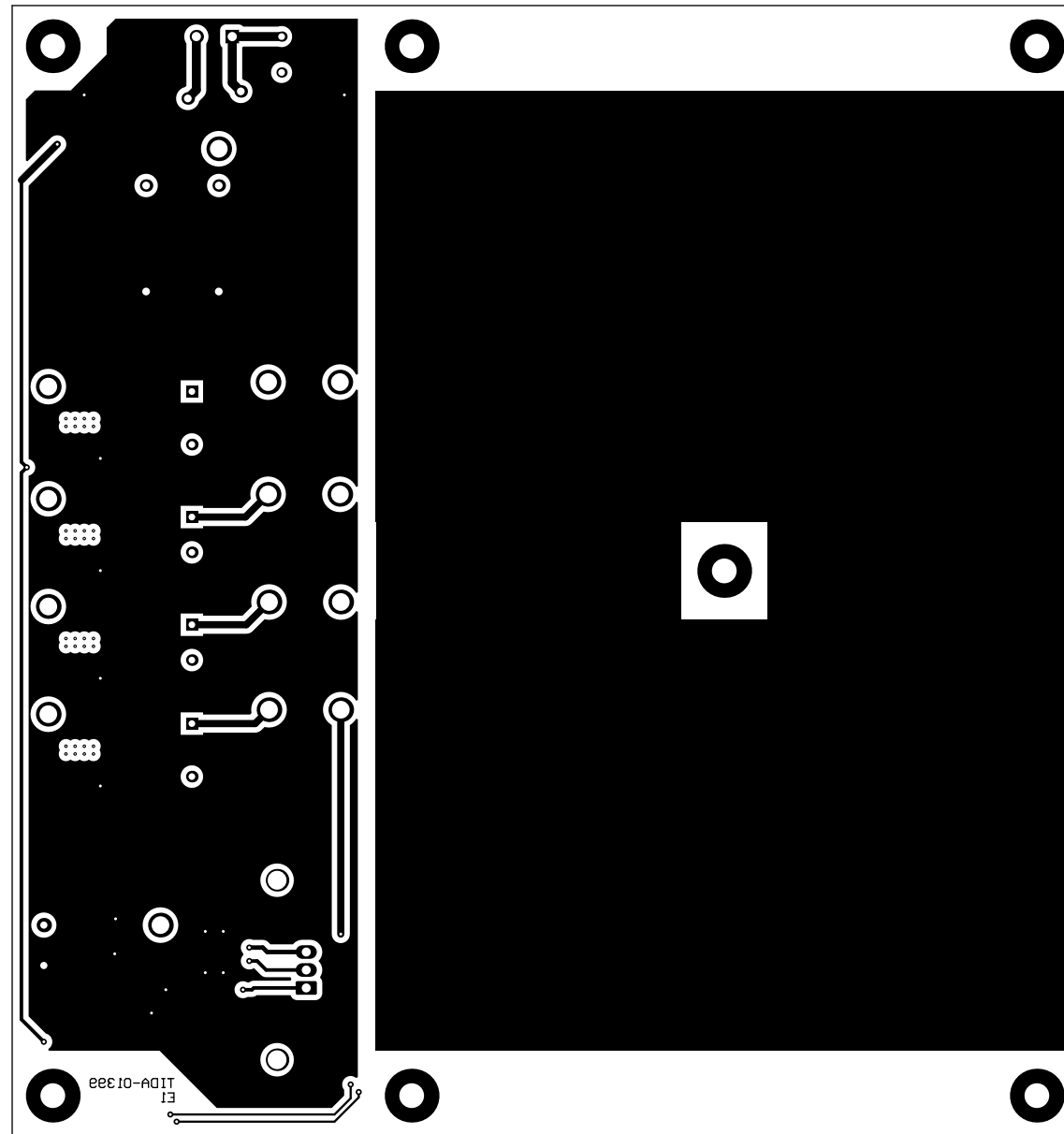
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 6/30/2017 1:52:05 PM	TEXAS INSTRUMENTS	



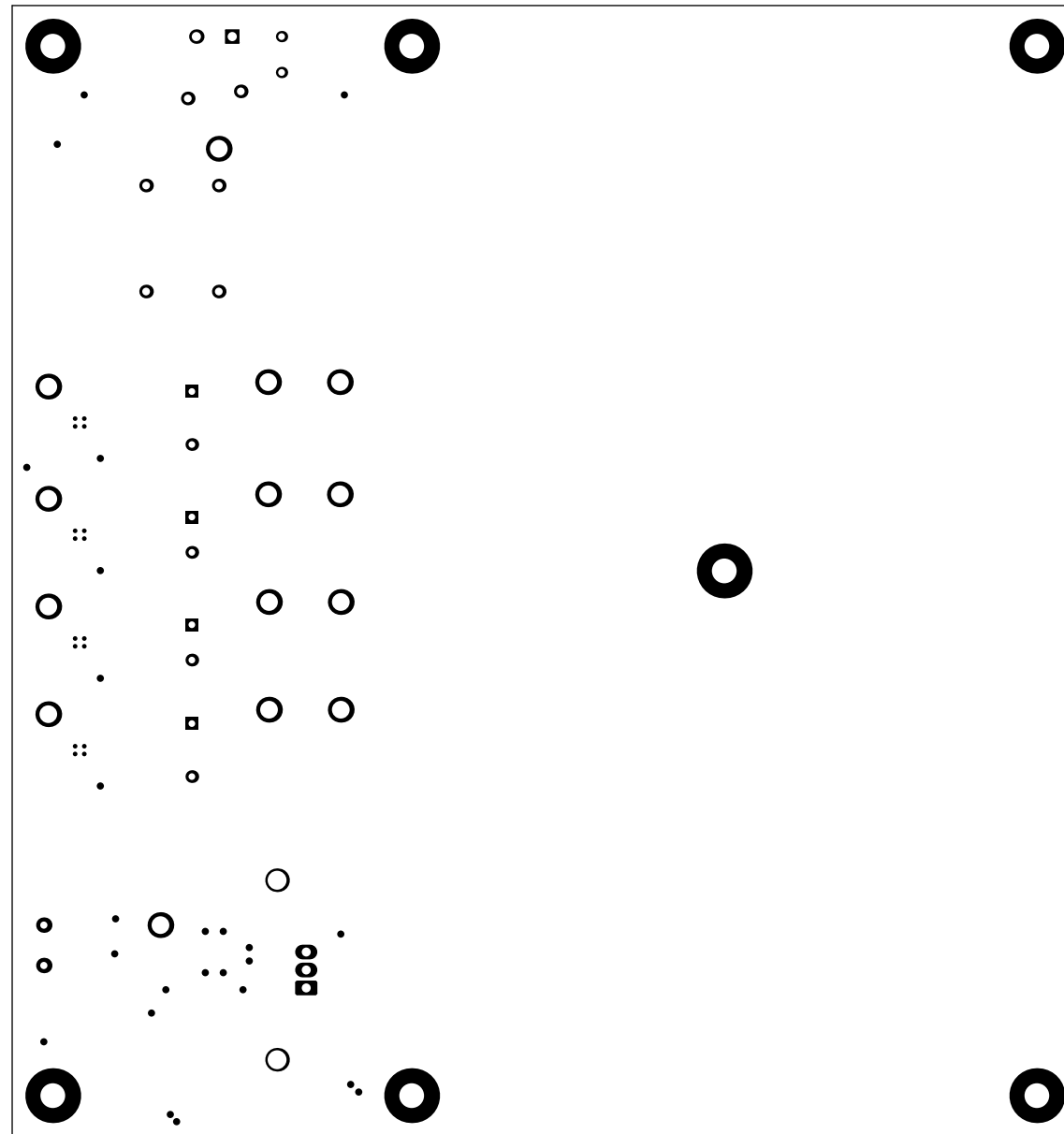
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer1			
PLOT NAME = MidLayer1	GENERATED : 6/30/2017 1:52:06 PM	TEXAS INSTRUMENTS	



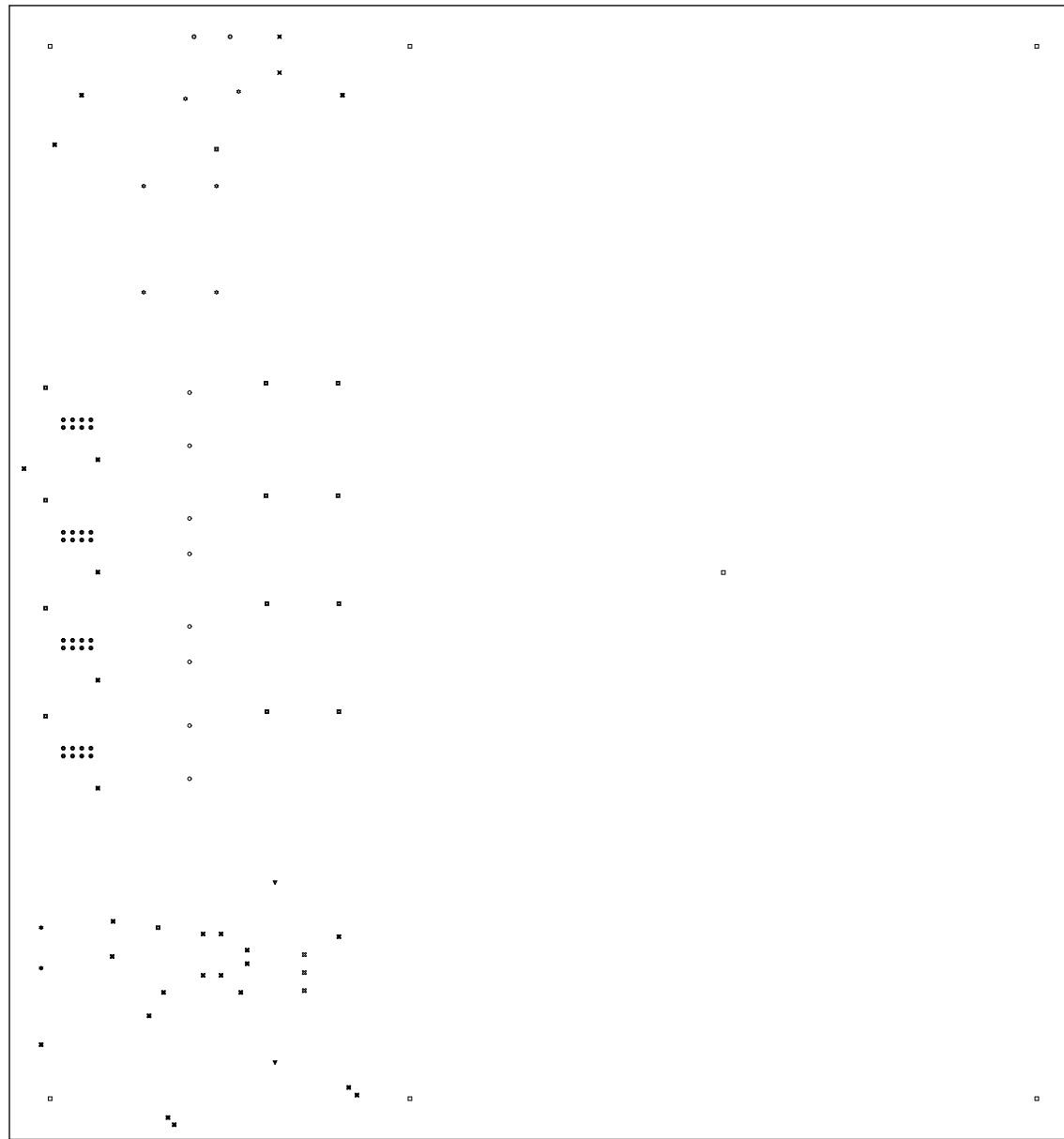
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = MidLayer2			
PLOT NAME = MidLayer2	GENERATED : 6/30/2017 1:52:07 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 6/30/2017 1:52:08 PM	TEXAS INSTRUMENTS	

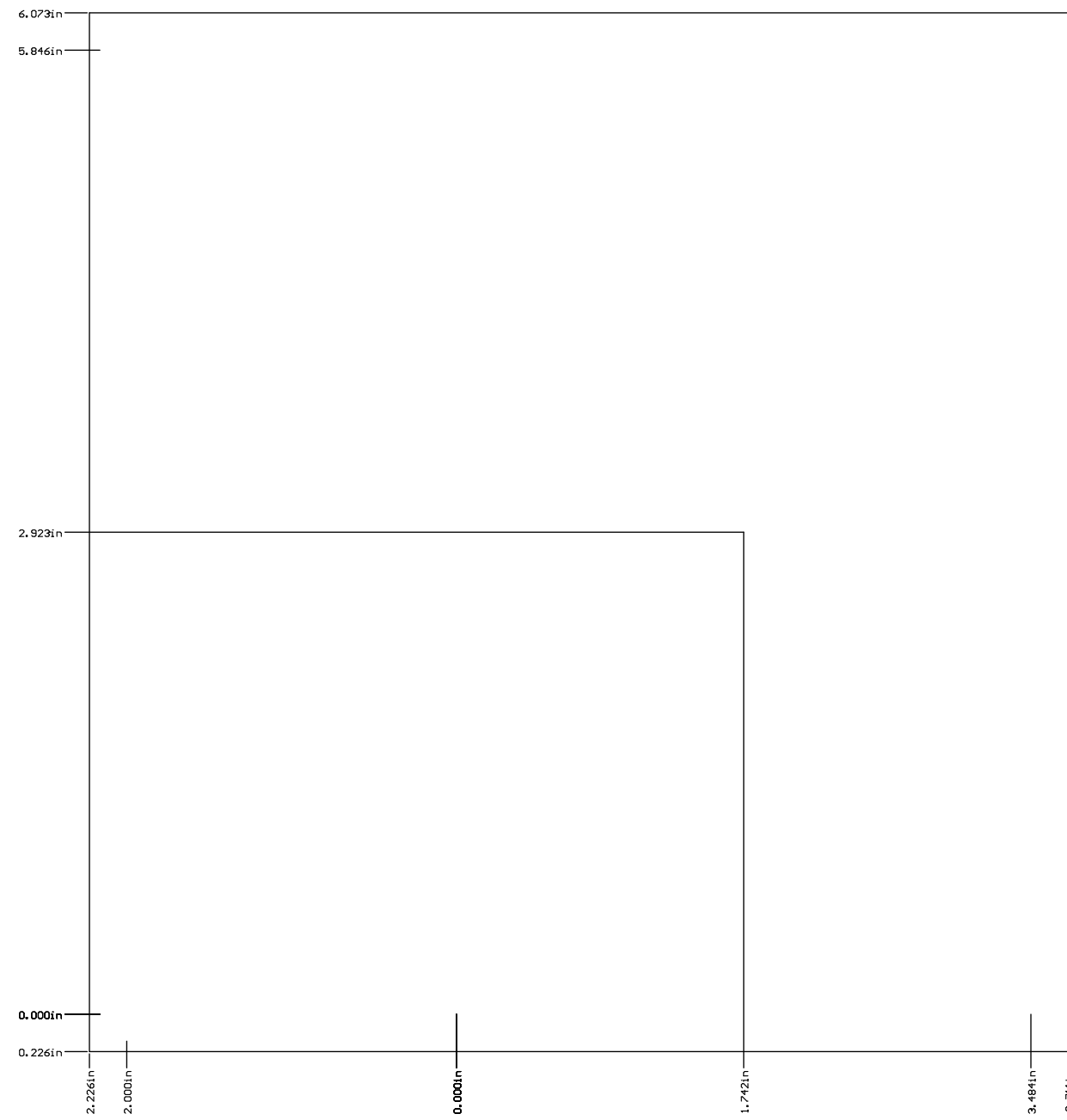


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 6/30/2017 1:52:09 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
□	7	137.80mil (3.500mm)	NPTH	Round	Top Layer - Bottom Layer	
⊗	32	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	25	16.00mil (0.406mm)	PTH	Round	Top Layer - Bottom Layer	
○	8	37.00mil (0.940mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	37.40mil (0.950mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	6	43.00mil (1.092mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	3	50.00mil (1.270mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	2	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	14	98.43mil (2.500mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	105.12mil (2.670mm)	PTH	Round	Top Layer - Bottom Layer	
	103 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 6/30/2017 1:52:10 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01399	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 6/30/2017 1:52:11 PM	TEXAS INSTRUMENTS	

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